

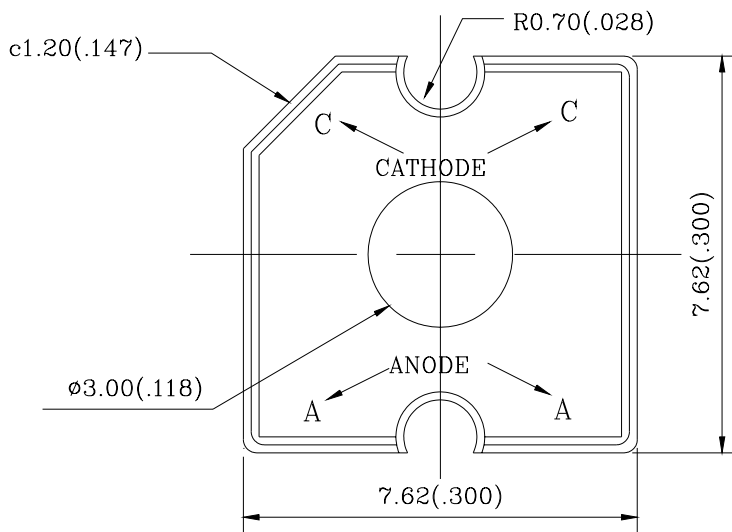


HIGH POWER LED LAMP

L-945VY3C

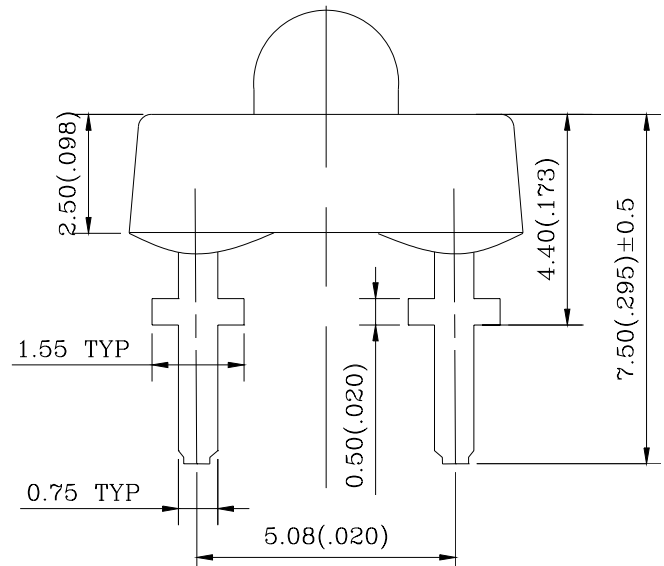
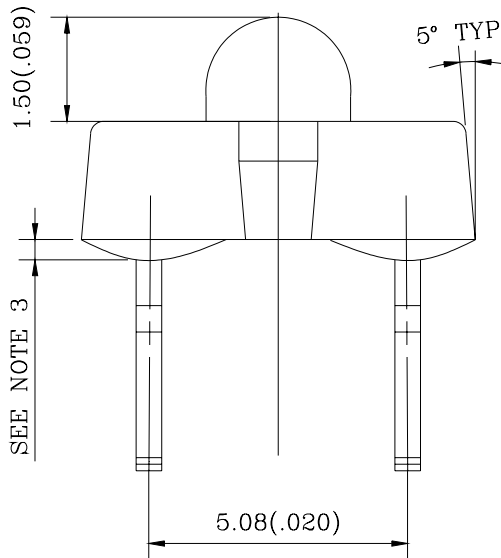
REV:A / 1

PACKAGE DIMENSIONS



Note:

1. All Dimensions are in millimeters.
2. Tolerance is $\pm 0.25\text{mm} (0.010 \text{ "})$ Unless otherwise specified.
3. Protruded resin under flange is 1.5mm (0.059 ") max.
4. Lead spacing is measured where the leads emerge from the package.
5. Specification are subject to change without notice





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FEATURES

- * HIGH POWER LED LAMP
- * HIGH FLUX OUTPUT
- * DESIGNED FOR HIGH CURRENT OPERATION
- * LOW THERMAL RESISTANCE
- * LOW PROFILE
- * RELIABLE
- * PACKAGED IN TUBES FOR USE WITH AUTOMATIC INSERTION EQUIPMENT

CHIP MATERIALS

- * Dice Material : AlGaInP/GaAs
- * Light Color : ULTRA YELLOW
- * Lens Color : WATER CLEAR

ABSOLUTE MAXIMUM RATING : (Ta = 25°C)

SYMBOL	PARAMETER	ULTRA YELLOW	UNIT
PAD	Power Dissipation Per Chip	130	mW
VR	Reverse Voltage Per Chip	5	V
IAF	Continuous Forward Current Per Chip	50	mA
—	Derating Linear From 25°C Per Chip	0.40	mA/°C
Topr	Operating Temperature Range	-25°C to 85°C	
Tstg	Storage Temperature Range	-40°C to 85°C	
Lead Soldering Temperature { 1.6mm(0.063 inch) From Body } 260°C ± 5°C for 5 Seconds			

ELECTRO-OPTICAL CHARACTERISTICS : (Ta = 25°C)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VF	Forward Voltage	IF = 20mA		2.15	2.6	V
IR	Reverse Current	VR = 5V			10	μA
λD	Dominant Wavelength	IF = 20mA		585		nm
Δλ	Spectral Line Half - Width	IF = 20mA		15		nm
2θ1/2	Half Intensity Angle	IF = 20mA		70		deg
ΦV	Total flux	IF = 50mA		5900		mlm



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